

Using the Design for Six Sigma (DFSS) Approach to Design, Test, and Evaluate to Reduce Program Risk

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Agenda

- **A Brief Six Sigma Primer**
- **The What and Why of Design for Six Sigma (DFSS)**
- **The DFSS Process**

Six Sigma Defined

Originally: Metric Based on the Statistical Measure Called Standard Deviation

Expanded To:

WORLD CLASS QUALITY

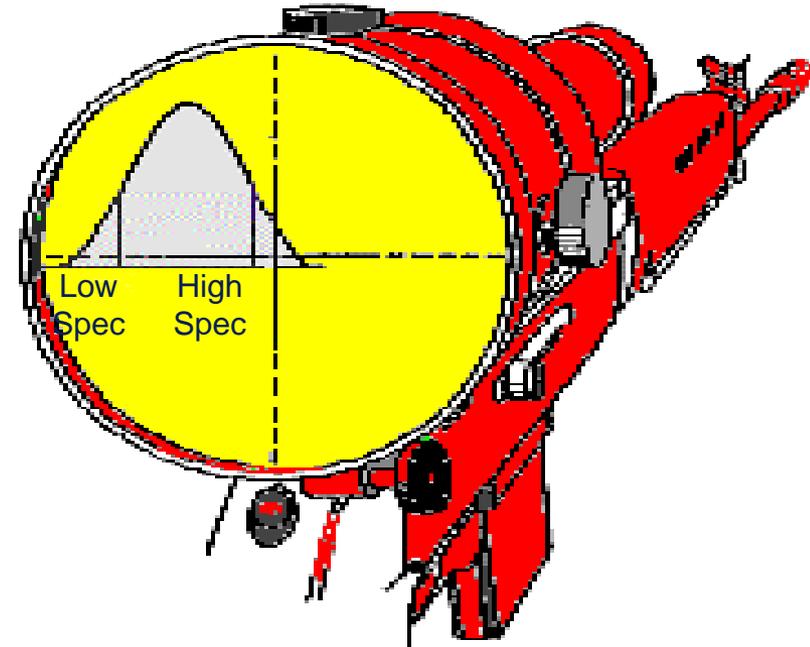
Providing a

BETTER product or service,

FASTER, and

at a LOWER COST

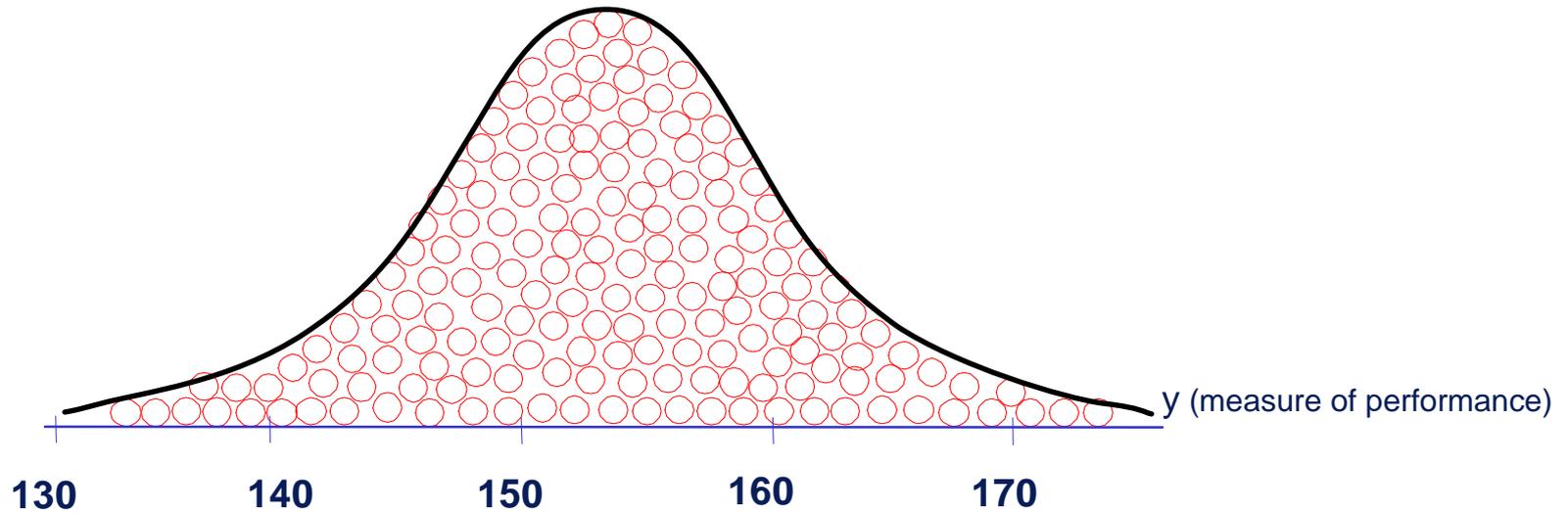
than our competition.



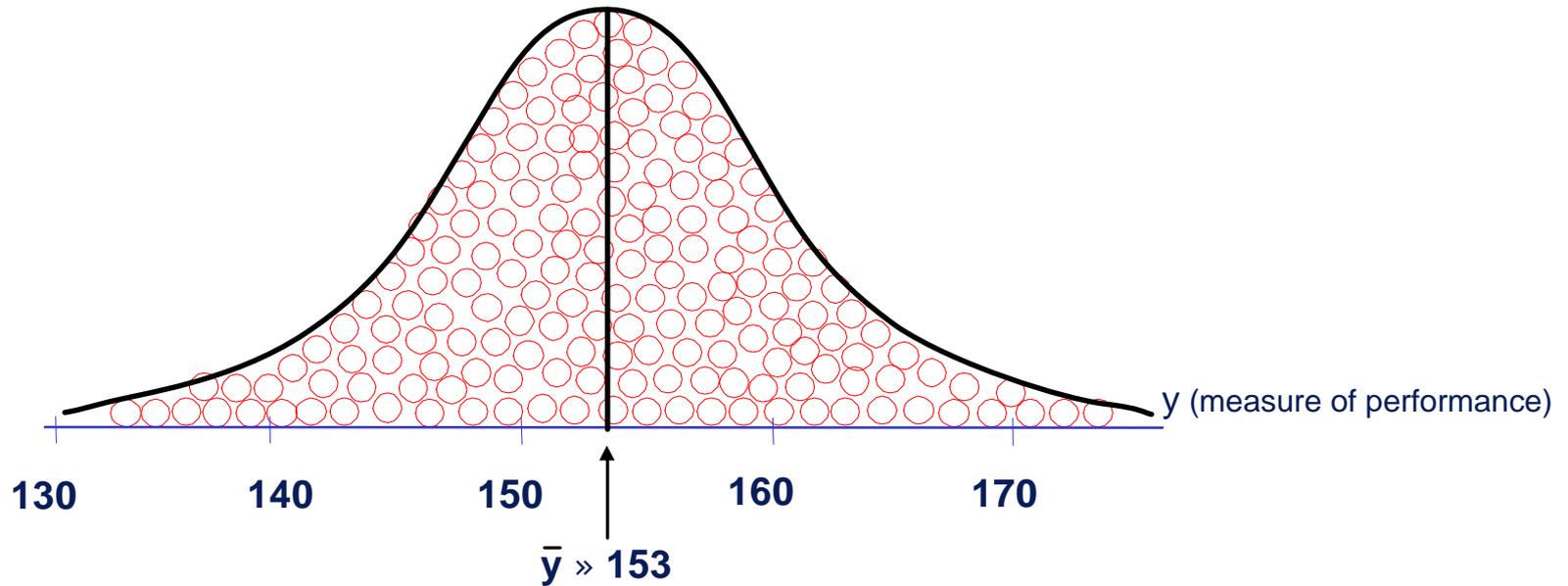
VARIATION is the enemy!

"Always know the language of the enemy."

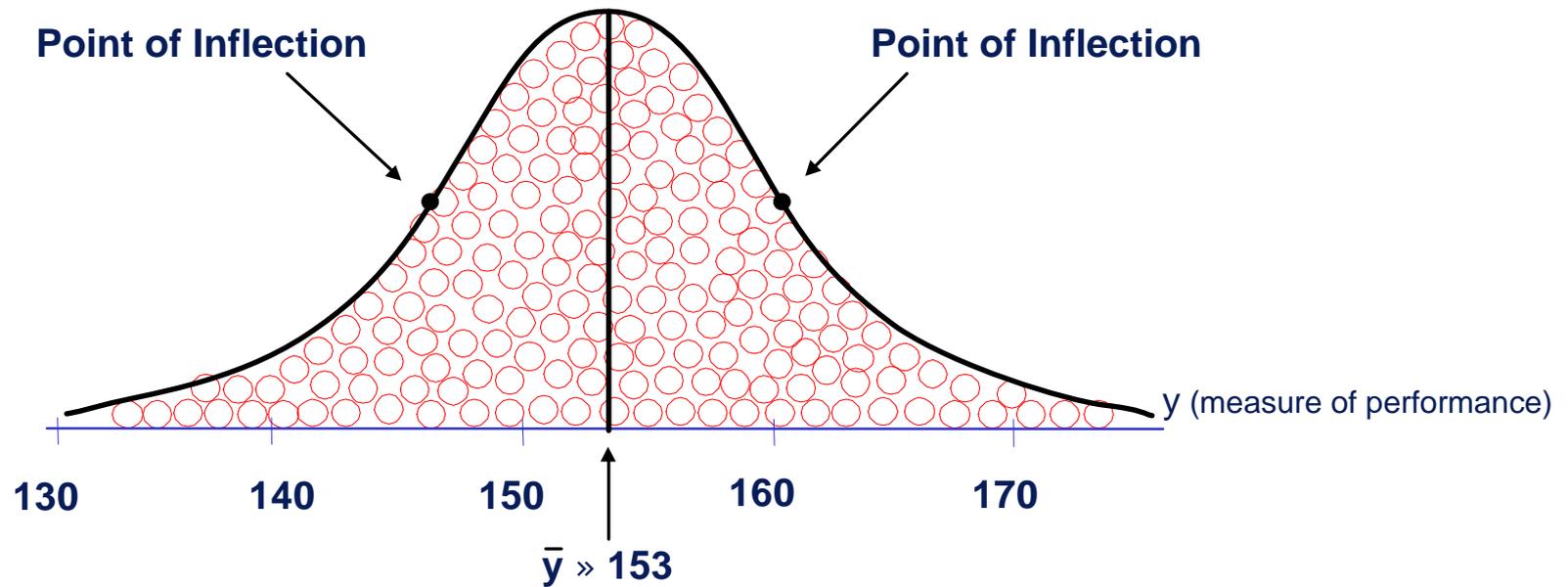
Graphical Meaning of a Distribution



Graphical Meaning of \bar{y}

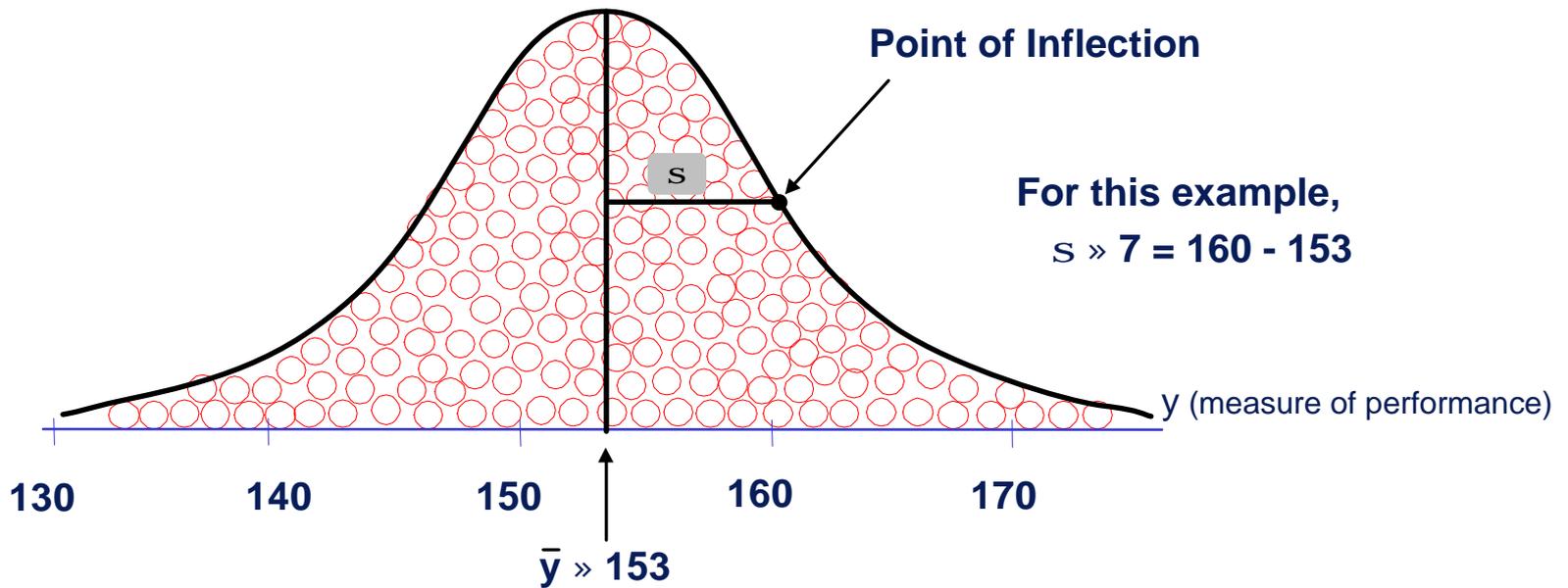


Graphical Meaning of Points of Inflection

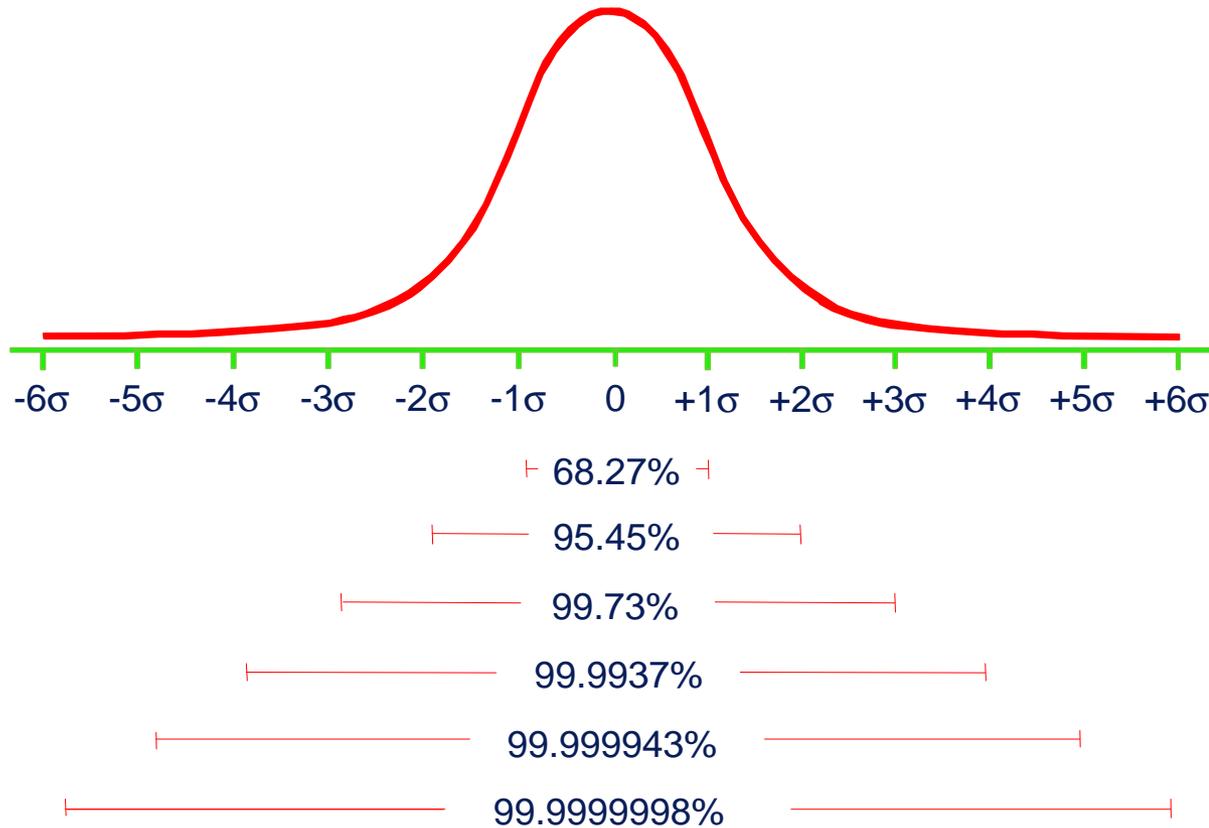


Graphical Meaning of s

s = distance from the center of the distribution to a point of inflection



Graphical View of Variation

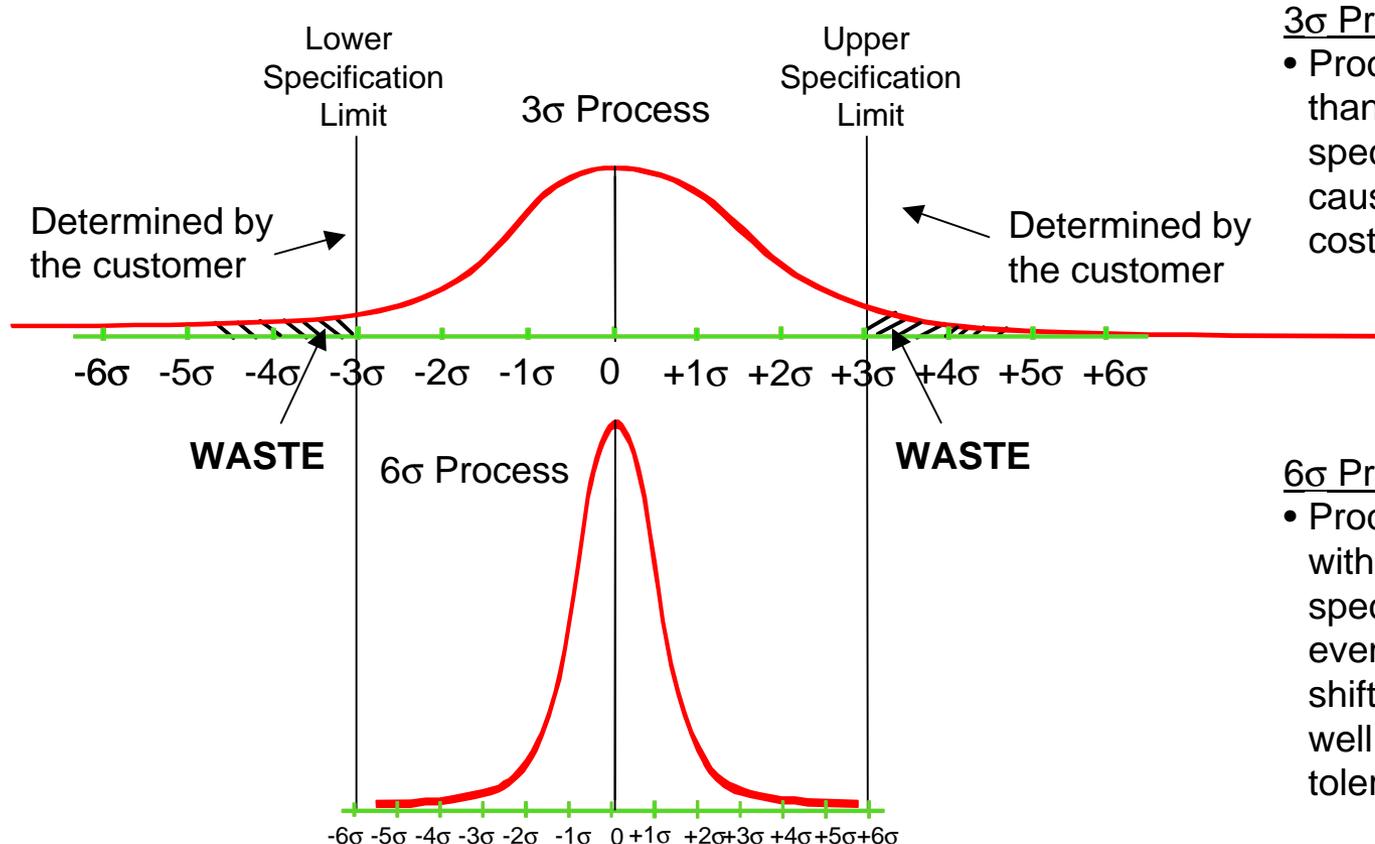


Typical Areas under the Normal Curve

Graphical View of Variation and Six Sigma Performance

The Sigma Capability of a process performance measure compares the Voice of the Process with the Voice of the Customer, and it is defined as follows:

The number of Sigmas between the center of a process performance measure distribution and the nearest specification limit



3 σ Process Centered

- Process is **WIDER** than the specifications, causing waste and cost of poor quality

6 σ Process Centered

- Process **FITS** well within the specifications, so even if the process shifts, the values fall well within tolerances

Six Sigma Measures Process Capability

Sigma Capability is a measure of process capability. It is correlated to the defect rate and the complexity of the process/product.

Yield is the probability that whatever we are producing (manufactured part, PO, shipped part, etc.) will pass through the entire process without rework and without defects.

σ Capability

DPMO

RTY

•	308,537	69.1%
•	66,807	93.3%
•	6,210	99.4%
•	233	99.97%
•	3.4	99.99966%

Process
Capability

Defects per Million
Opportunities

Rolled Throughput
Yield

**Six Sigma is a standard of Excellence.
It means less than 4 Defects per Million Opportunities.**

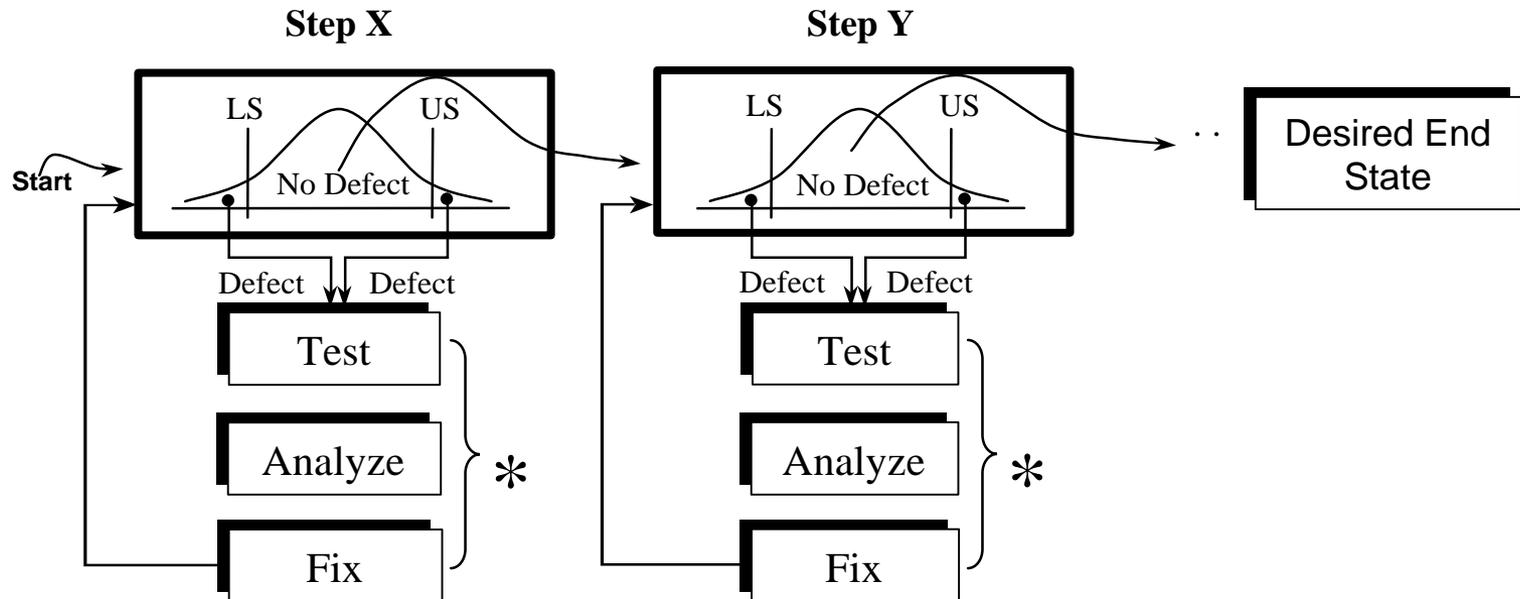
Relationship Between Lean and Six Sigma

# of Parts (Steps)	OVERALL YIELD vs SIGMA (Distribution Shifted $\pm 1.5s$)			
	$\pm 3S$	$\pm 4S$	$\pm 5S$	$\pm 6S$
1	93.32%	99.379%	99.9767%	99.99966%
7	61.63	95.733	99.839	99.9976
10	50.08	93.96	99.768	99.9966
20	25.08	88.29	99.536	99.9932
40	6.29	77.94	99.074	99.9864
60	1.58	68.81	98.614	99.9796
80	0.40	60.75	98.156	99.9728
100	0.10	53.64	97.70	99.966
150	---	39.38	96.61	99.949
200	---	28.77	95.45	99.932
300	---	15.43	93.26	99.898
400	---	8.28	91.11	99.864
500	---	4.44	89.02	99.830
600	---	2.38	86.97	99.796
700	---	1.28	84.97	99.762
800	---	0.69	83.02	99.729
900	---	0.37	81.11	99.695
1000	---	0.20	79.24	99.661
1200	---	0.06	75.88	99.593
3000	---	---	50.15	98.985
17000	---	---	1.91	94.384
38000	---	---	0.01	87.880
70000	---	---	---	78.820
150000	---	---	---	60.000

**Use for
Benchmarking**

Source: Six Sigma RESEARCH INSTITUTE
Motorola University Motorola, Inc.

How Process Capability Impacts Cycle Time and Resource Allocation



Every Time a Defect is Created During a Process (Step), it Takes Additional Cycle Time to Test, Analyze, and Fix.

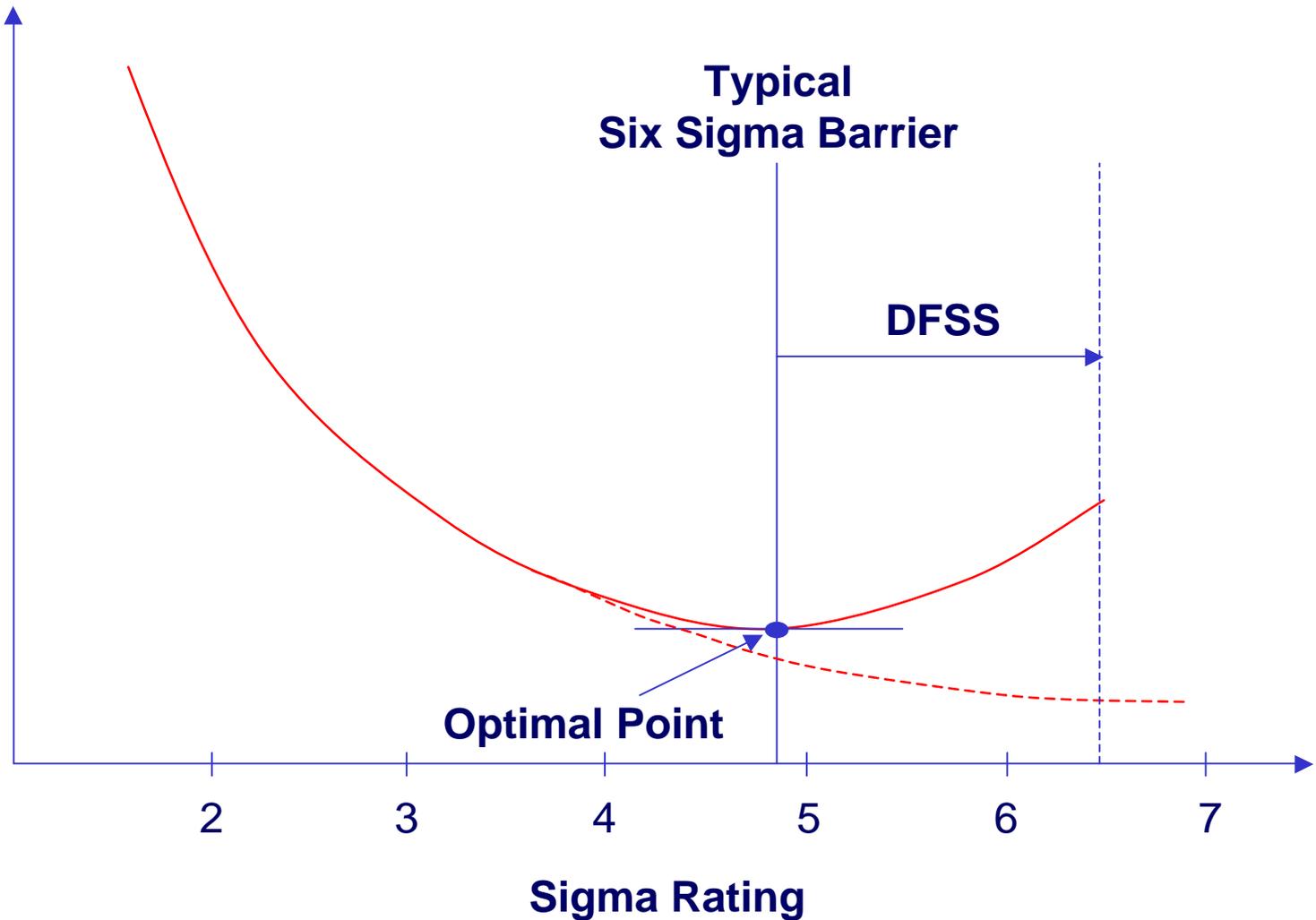
* These Non-Value Added Activities Typically Require Additional Floor Space, Capital Equipment, Material, and People.

Six Sigma Project Phases

- **D**efine the problem / defects
- **M**easure the current performance level
- **A**nalyze to determine the root causes of the problem / defects
- **I**mprove by identifying and implementing solutions that eliminate root causes
- **C**ontrol by monitoring the performance of the improved process

What Have We Learned From Six Sigma?

Total Cost



Food for Thought...

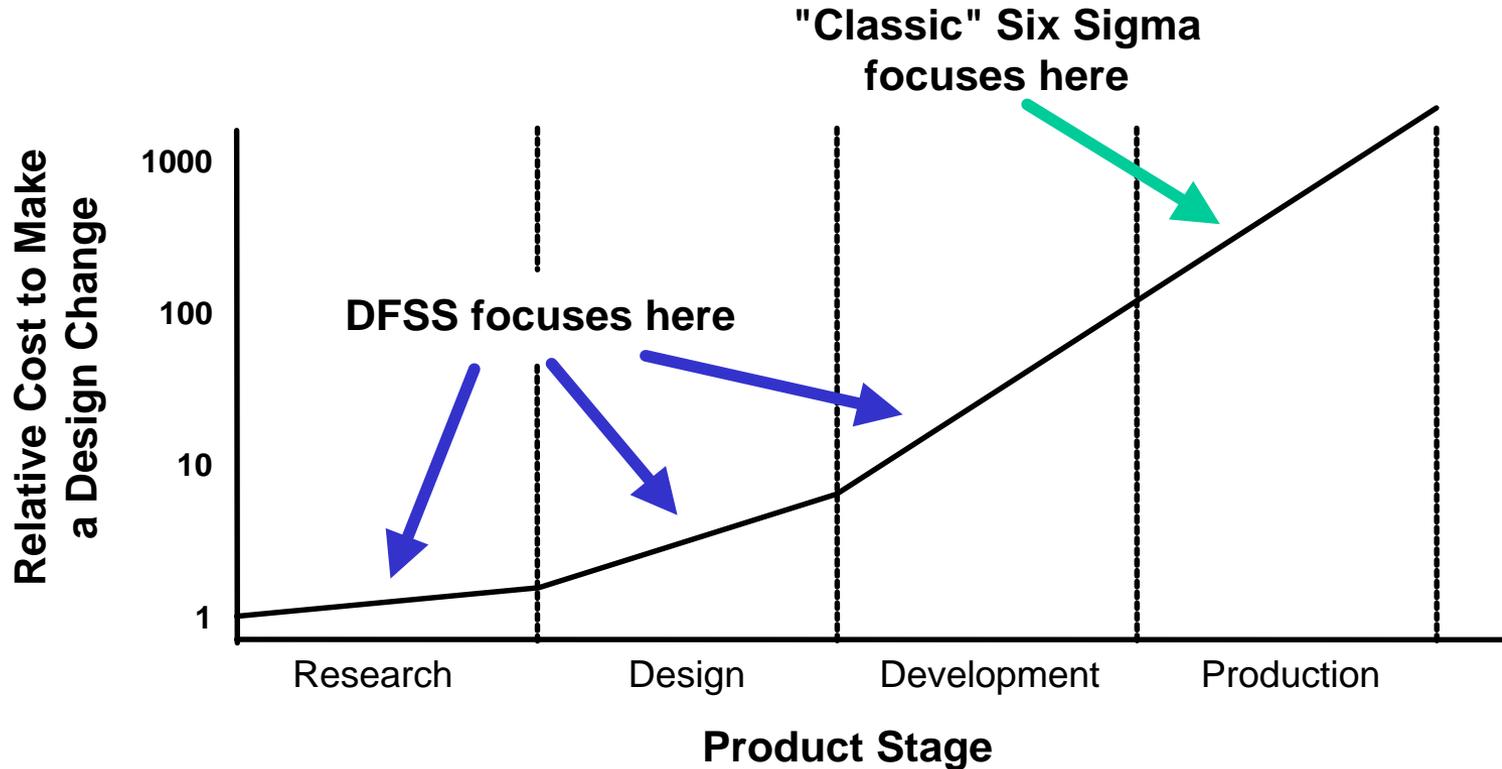
the systems and products that deliver value to our customers are perfectly designed to achieve the results we are getting today.

DFSS – What is it?

Design For Six Sigma is:

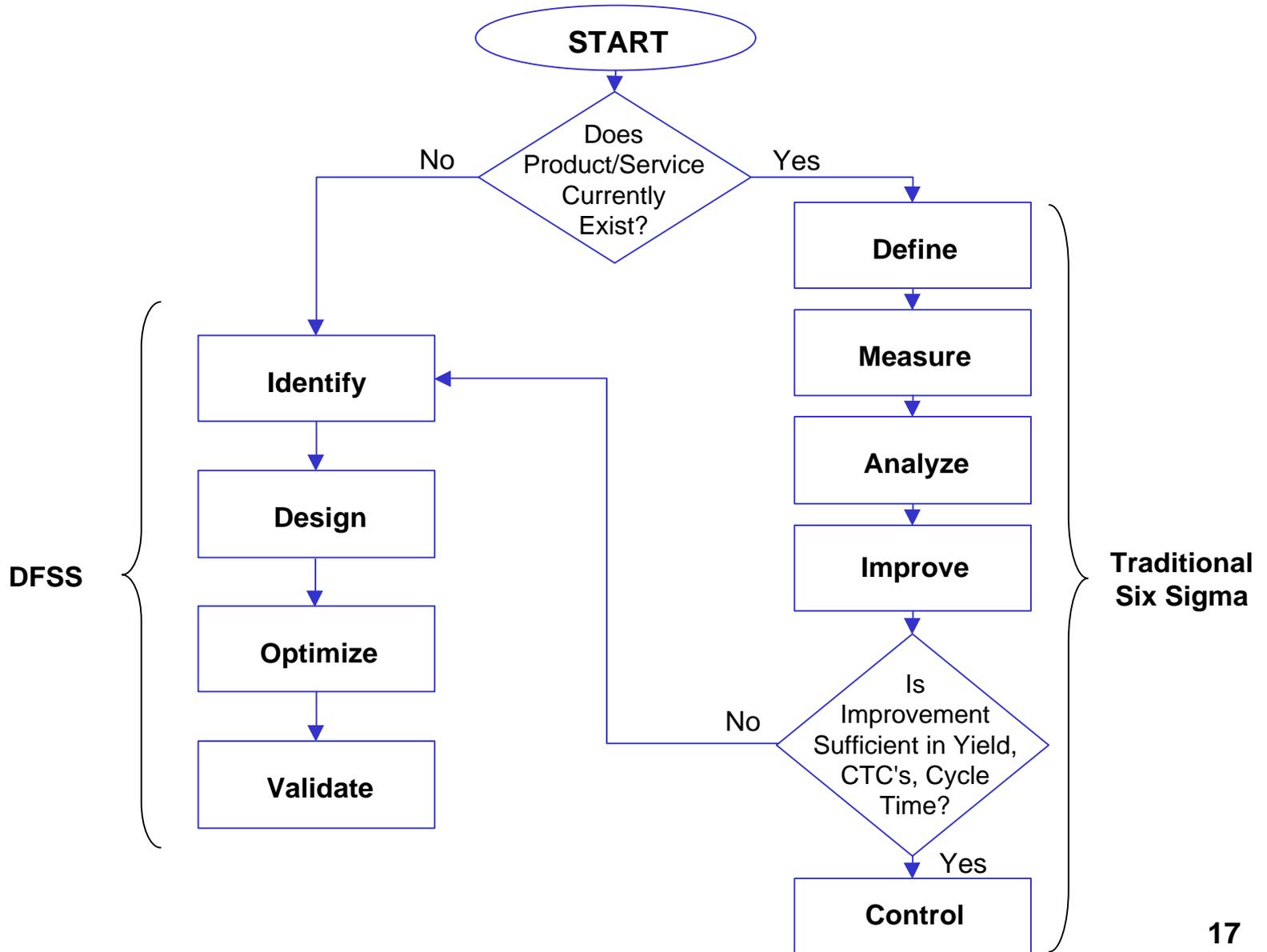
- A methodology for designing new products and/or processes.
- A methodology for re-designing existing products and/or processes.
- A way to implement the Six Sigma methodology as early in the product or service life cycle as possible.
- A way to exceed customer expectations.
- A way to gain market share.
- A strategy toward extraordinary ROI.

Why DFSS



- "Design in" quality when costs are lowest
- Show customers "Six Sigma" products right from the start

The Big Picture

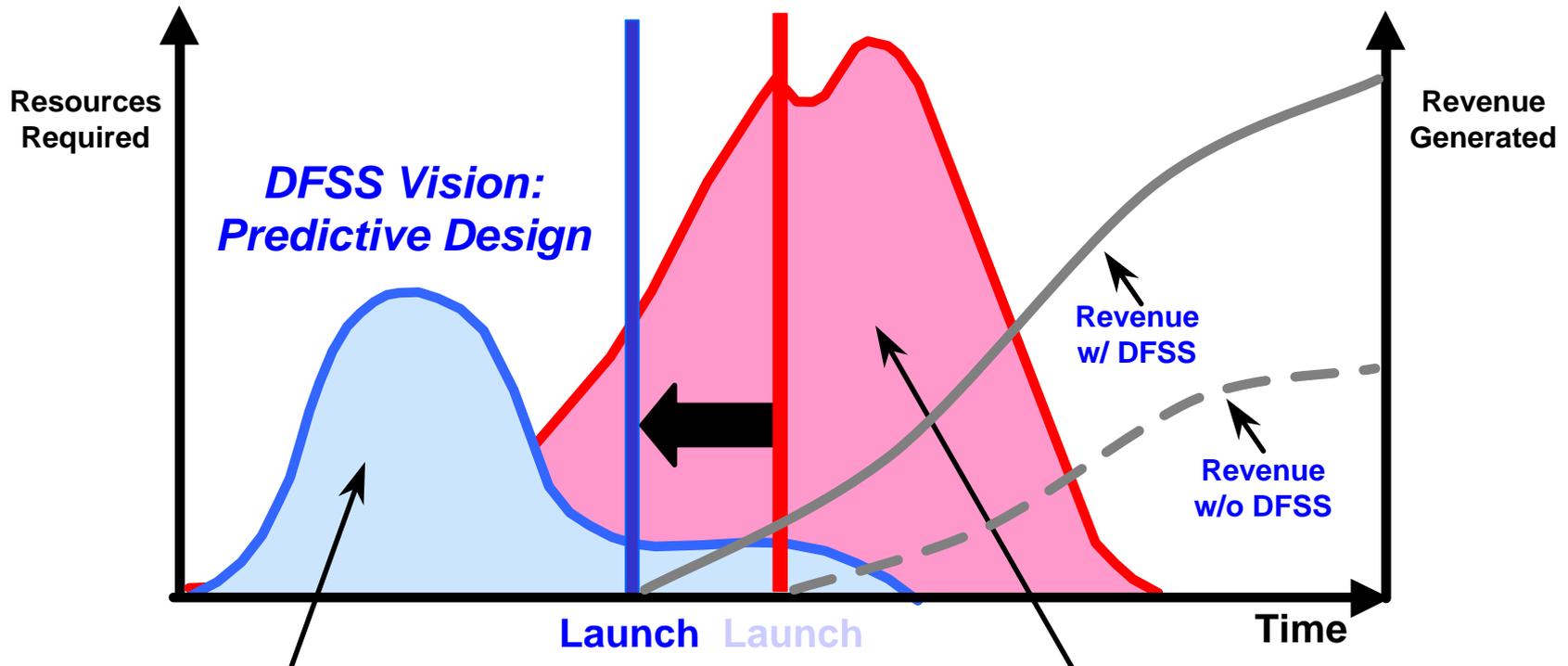


The Benefits of DFSS

- **Goal: Create new *game-changing* products and services which**
 - Wow customers with *6s performance* on their CTCs
 - Have *6s reliability*
 - Have *6s manufacturability*
 - Have *high performance/cost ratios*
- **Payoffs**
 - *Quality designed in* from the start
 - Revenue *growth*: customer delight, market share, volume, price
 - Warranty cost reductions

Driver for growth

The Opportunity of DFSS



- Early problem identification; solution when costs low
- Faster market entry: earlier revenue stream, longer patent coverage
- Lower total development cost
- Robust product at market entry: delighted customers
- Resources available for next game-changer

Pre-DFSS: Reactive Design

- Unhappy customers
- Unplanned resource drain
- Skyrocketing costs
- Next product compromised

- Upfront investment is most effective and efficient
- Show customers “6s” products right from the start

The Vision of DFSS



From

- Evolving design requirements
- Extensive design rework
- Product performance assessed by “build and test”
- Performance and producibility problems fixed after product in use
- Quality “tested in”

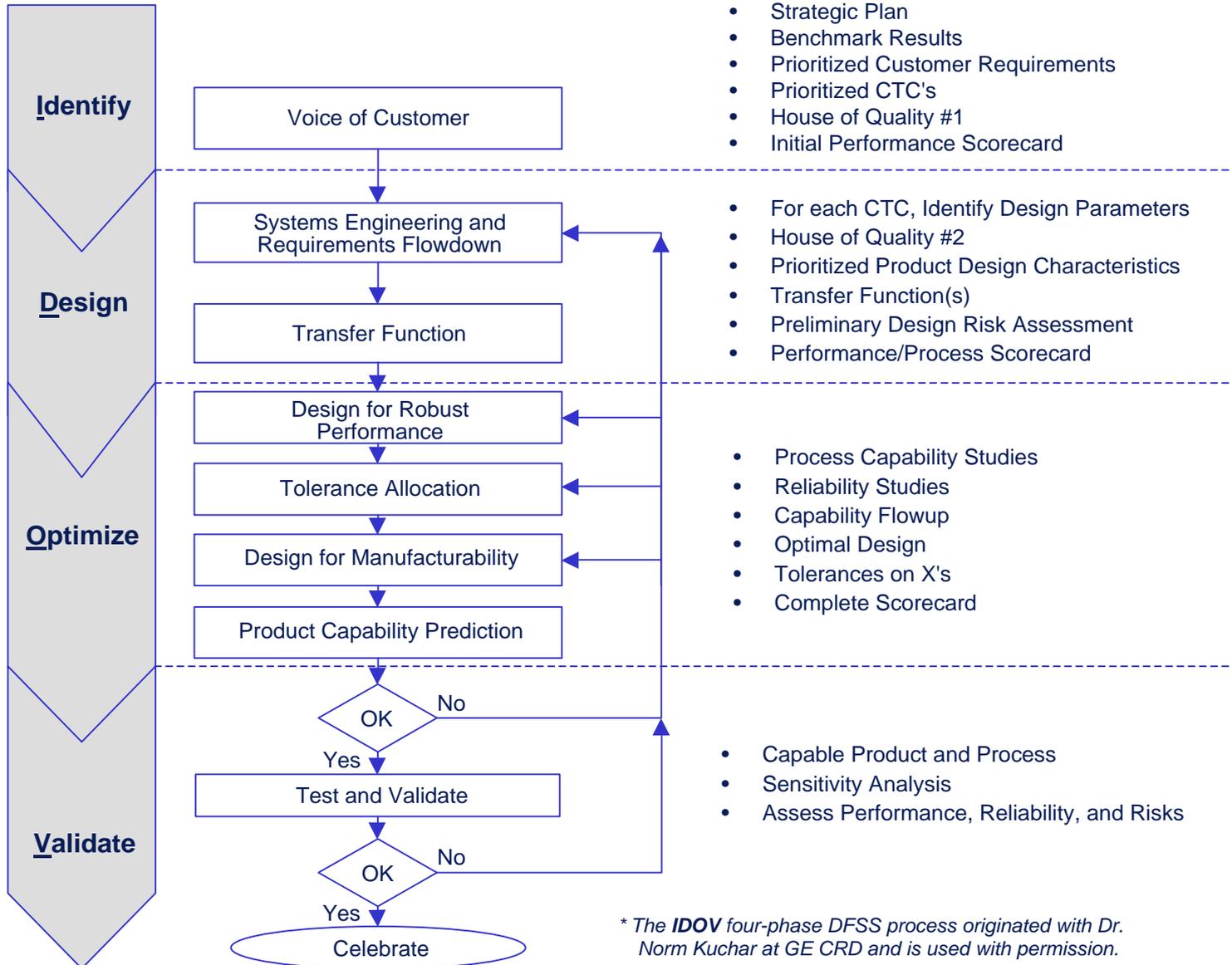


To

- Disciplined CTC flowdown
- Controlled design parameters
- Product performance modeled and simulated
- Designed for robust performance and producibility
- Quality “designed in”

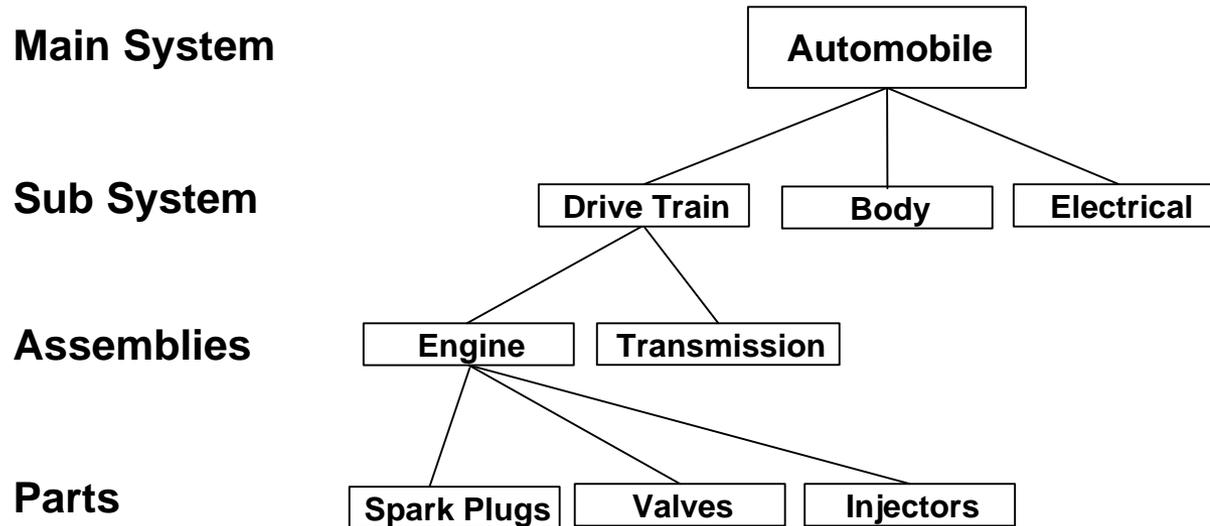
- 6 s products everywhere
- Revolutionize Engineering

DFSS Process



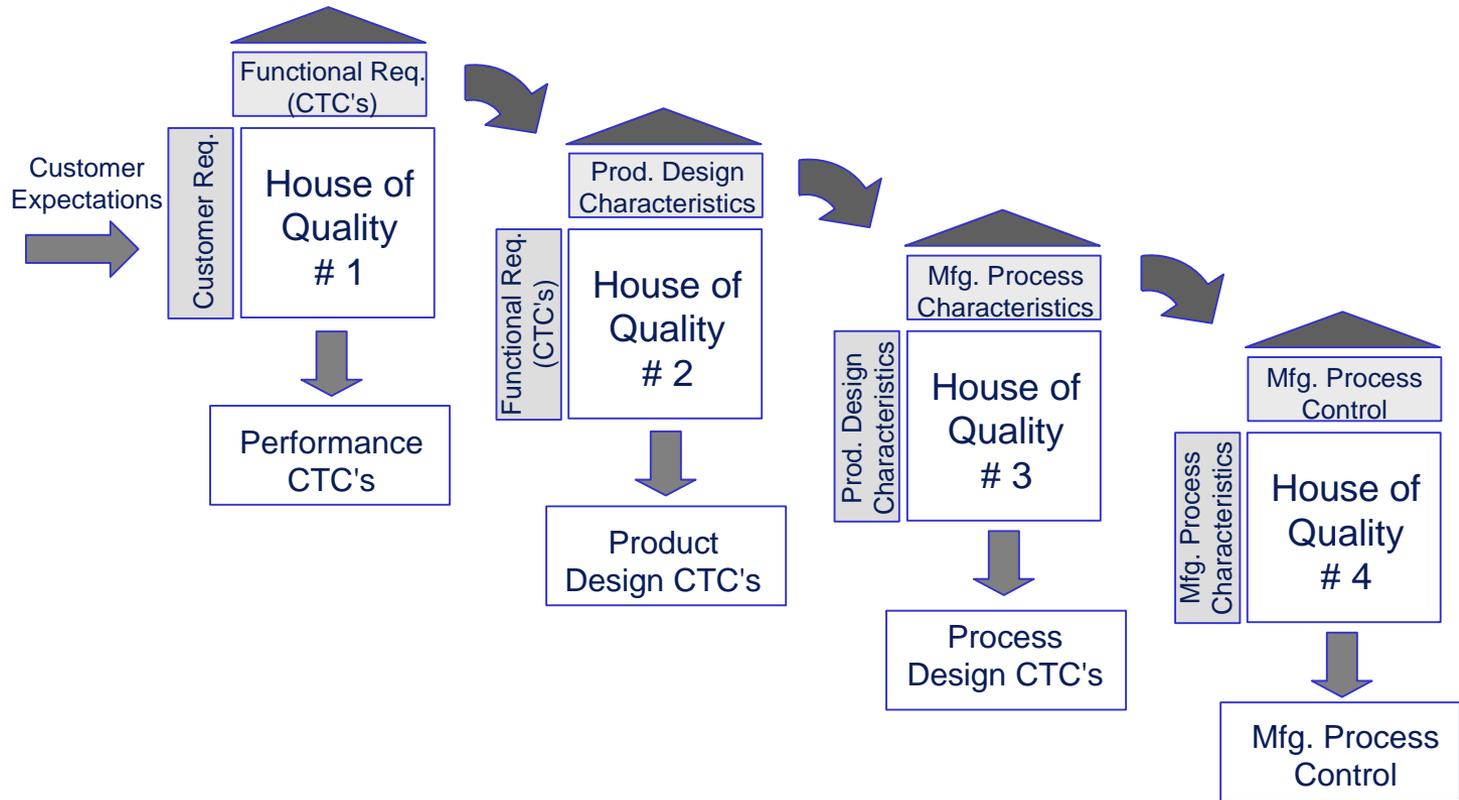
* The **IDOV** four-phase DFSS process originated with Dr. Norm Kuchar at GE CRD and is used with permission.

Systems Engineering



- **Complex products may require the "Divide and Conquer" approach.**
- **Flow the system requirements down and roll the capability up.**
- **System Engineers are the masters of the scorecard and make tradeoff decisions.**

DFSS and Six Sigma



Marketing

- Features
- Quality
- Performance
- Cost

Design Engineering

- Performance
- Reliability
- Cost

Mfg. Engineering

- Manufacturability
- Cost

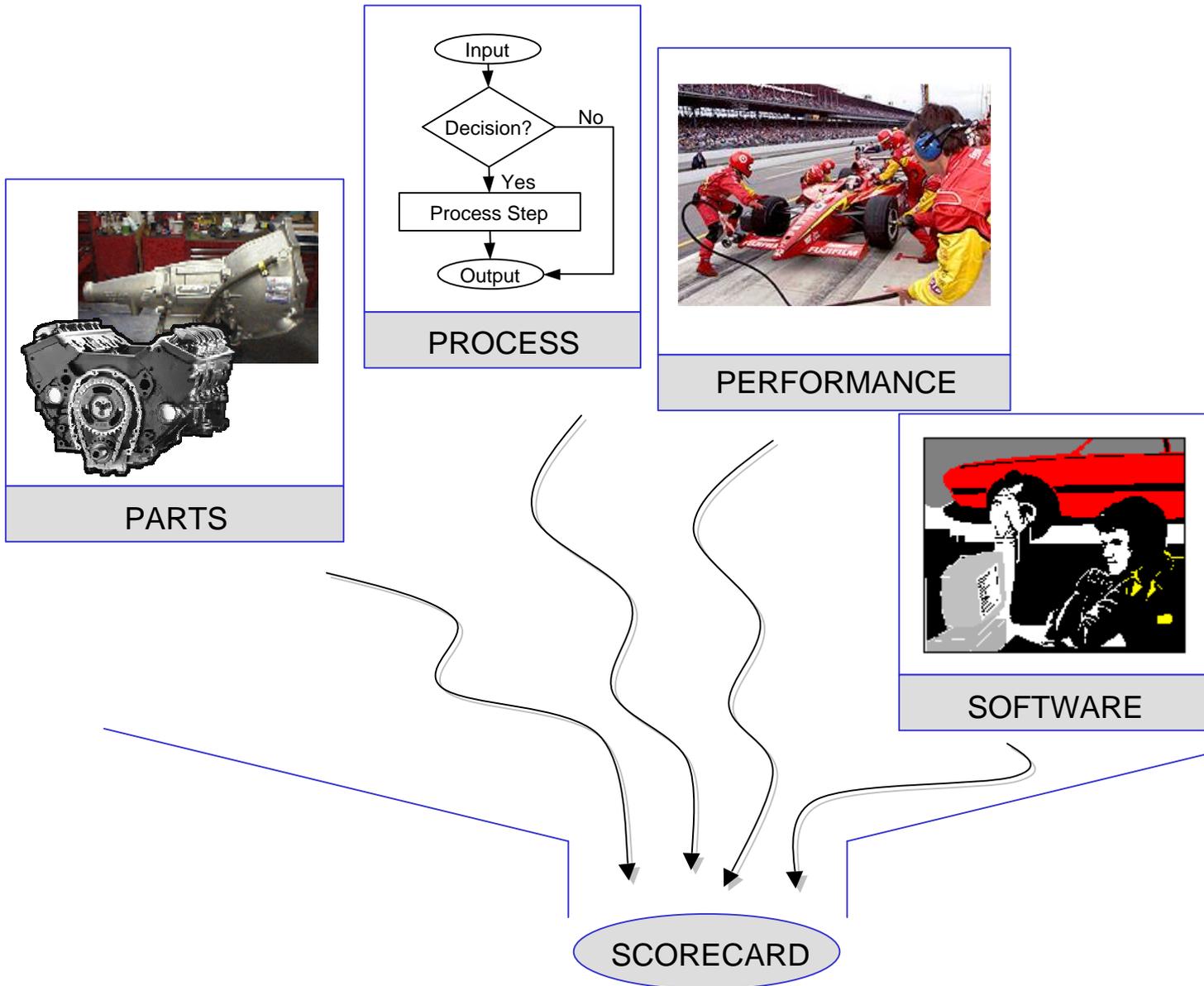
Manufacturing

- SPC
- Process Capability

DFSS

Six Sigma

Scorecard Components



Scorecard Example

SOLENOID PART SCORECARD

#	Part Name	DPU	Qty	Continuous Variable						Sample Size Known		ppm Only ppm
				Target	Mean	Std Dev	LSL	USL	UOM	Sample Size	# Defective	
1	Wire	0.0000220	1									22
2	Power Supply	0.0008582	1	1.1	1.1	0.015	1.05	1.15	Amps			
3	Core (Length)	0.0000044	1	15	15	0.45	13	18	cm			
4	Core (Radius)	0.0008582	1	2	2	0.3	1	3	cm			
5												
6												
7												

SOLENOID PROCESS SCORECARD

#	Process Step	DPU	Qty	Continuous Variable						Sample Size Known		ppm Only ppm
				Target	Mean	Std Dev	LSL	USL	UOM	Sample Size	# Defective	
1	Apply Wire to Core	0.000063	1	110	110	1	106	114	Twist			
2	Attach Power Supply	0.000200	1							10000	2	
3												
4												
5												
6												

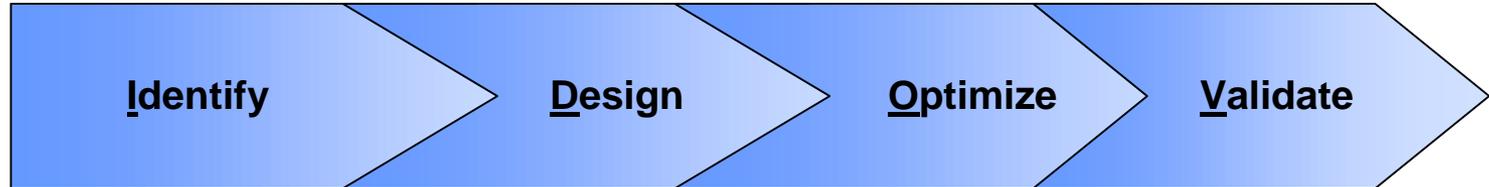
SOLENOID PERFORMANCE SCORECARD

#	Performance	DPU	Qty	Continuous Variable						Sample Size Known		ppm Only ppm
				Target	Mean	Std Dev	LSL	USL	UOM	Sample Size	# Defective	
1	Mag Force 4cm from center	0.0000921	1	7.5	7.47	0.254	6.5	8.5	Amp/cm			
2												
3												
4												

Solenoid Scorecard (cont.)

Scorecard Summary						
	# Steps/Parts	Total dpu	Yield	dpmo	ST Sigma	LT Sigma
Part	4	0.001743	99.826%	435.72	4.8289	3.3289
Process	2	0.000263	99.974%	131.69	5.1485	3.6485
Performance Software	1	0.000092	99.991%	92.12	5.2393	3.7393
Total	7	0.002098363	99.790%	299.766	4.932	3.432

DFSS Tools



Identify	Design	Optimize	Validate
Project Charter	Assign Specifications to CTC's	Histogram	Sensitivity Analysis
Strategic Plan	Customer Interviews	Distributional Analysis	Gap Analysis
Cross-Functional Team	Formulate Design Concepts	Empirical Data Distribution	FMEA
Voice of the Customer	Pugh Concept Generation	Expected Value Analysis (EVA)	Fault Tree Analysis
Benchmarking	TRIZ or ASIT	Adding Noise to EVA	Control Plan
KANO's Model	Pugh Concept Synthesis	Non-Normal Output Distributions	PF/CE/CNX/SOP
Questionnaires	Controlled Convergence	Design of Experiments	Run/Control Charts
Focus Groups	FMEA	Multiple Response Optimization	Mistake Proofing
Interviews	Fault Tree Analysis	Robust Design Development	MSA
Internet Search	Brainstorming	Using S-hat Model	Reaction Plan
Historical Data	QFD	Using Interaction Plots	
Quality Function Deployment	Scorecard	Using Contour Plots	
Pairwise Comparison	Transfer Function	Parameter Design	
Design of Experiments	Design of Experiments	Tolerance Allocation	
Specify CTC's	Deterministic Simulators	Reducing Standard Deviations of Inputs	
Performance Scorecard	Confidence Intervals	Design For Manufacturability	
Flow Charts	Hypothesis Testing	Mistake Proofing	
FMEA	MSA	Product Capability Prediction	
Visualization	Computer Aided Design	Part, Process, and SW Scorecard	
	Computer Aided Engineering	Risk Assessment	
	High Throughput Testing	Reliability	
		Multidisciplinary Design Optimization (MDO)	

High Throughput Testing (HTT)

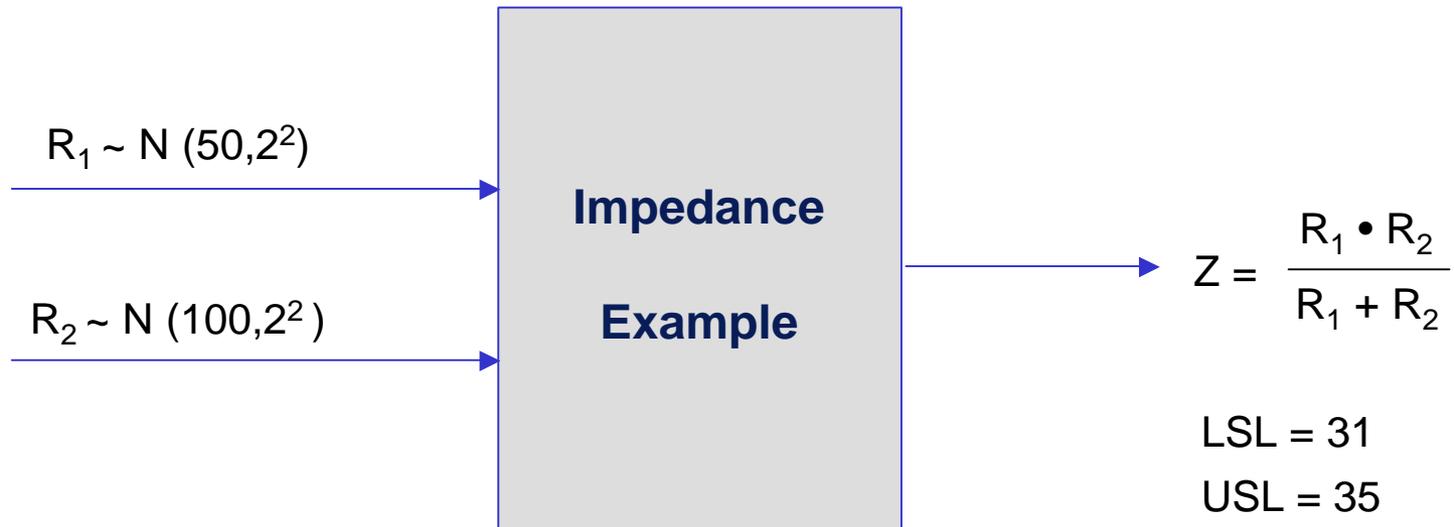
(for all two-way combinations)

Full Factorial = 8100 runs

HTT = 27 runs

<i>5 Levels</i> Motherboard	<i>3 Levels</i> Ram	<i>3 Levels</i> BIOS	<i>3 Levels</i> CD	<i>5 Levels</i> Monitor	<i>3 Levels</i> Printer	<i>2 Levels</i> Voltage	<i>2 Levels</i> Resolution
Gateway	128 MB	Dell	Generic	Viewsonic	HP	220V	800 by 600
ASUS	256 MB	Award	Teac	Sony	Lexmark	110V	800 by 600
Micronics	512 MB	Dell	Sony	KDS	Cannon	110V	1024 by 768
Dell	128 MB	Generic	Teac	NEC	Lexmark	220V	1024 by 768
Compaq	256 MB	Generic	Sony	Generic	HP	110V	800 by 600
Dell	256 MB	Award	Generic	Viewsonic	Cannon	110V	1024 by 768
ASUS	512 MB	Award	Sony	Sony	HP	220V	1024 by 768
Micronics	128 MB	Award	Teac	Generic	Cannon	220V	800 by 600
Gateway	256 MB	Award	Teac	KDS	HP	220V	800 by 600
Compaq	512 MB	Dell	Teac	Viewsonic	Lexmark	220V	800 by 600
Gateway	128 MB	Generic	Sony	Sony	Cannon	110V	1024 by 768
Dell	256 MB	Dell	Sony	NEC	HP	110V	800 by 600
ASUS	128 MB	Generic	Generic	KDS	Lexmark	110V	800 by 600
Micronics	256 MB	Generic	Sony	Viewsonic	Lexmark	110V	800 by 600
Compaq	512 MB	Award	Generic	NEC	Cannon	110V	1024 by 768
ASUS	512 MB	Dell	Generic	Generic	Lexmark	110V	1024 by 768
Micronics	128 MB	Dell	Generic	Sony	HP	110V	800 by 600
Dell	512 MB	Generic	Teac	Sony	HP	110V	800 by 600
Gateway	512 MB	Award	Teac	NEC	Lexmark	110V	800 by 600
ASUS	128 MB	Award	Teac	Viewsonic	Cannon	110V	800 by 600
Compaq	128 MB	Award	Teac	Sony	HP	110V	800 by 600
Dell	128 MB	Award	Teac	KDS	HP	110V	800 by 600
ASUS	128 MB	Award	Teac	NEC	HP	110V	800 by 600
Dell	128 MB	Award	Teac	Generic	HP	110V	800 by 600
Micronics	128 MB	Award	Teac	NEC	HP	110V	800 by 600
Compaq	128 MB	Award	Teac	KDS	HP	110V	800 by 600
Gateway	128 MB	Award	Teac	Generic	HP	110V	800 by 600

Tolerance Allocation Example



If we were able to change a resistor's standard deviation, which resistor, R_1 or R_2 , would have the greater impact on the dpm of Z (impedance)?

Tolerance Allocation Example (cont.)

A reduction of R_1 by 50% reduces dpm by an order of magnitude X, while R_2 has little impact.

Tolerance Allocation Table		
N = 10,000 (in defects per million)		
Impedance Table		
	R1	R2
-50% Sigma	372.40	34,683
-25% Sigma	8,058	36,849
-10% Sigma	23,906	35,663
Nominal	39,220	39,657
+10% Sigma	59,508	37,556
+25% Sigma	92,398	47,317
+50% Sigma	148,113	46,801

A reduction of R_1 's standard deviation by 50% combined with an increase in R_2 's standard deviation by 50%

$$R_1 \sim N(50, 1^2)$$

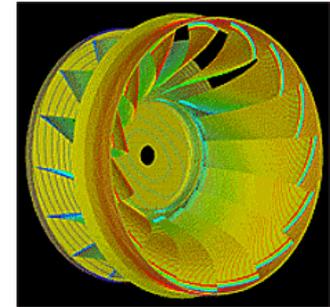
$$R_2 \sim N(100, 3^2)$$

results in a dpm = 1,254.

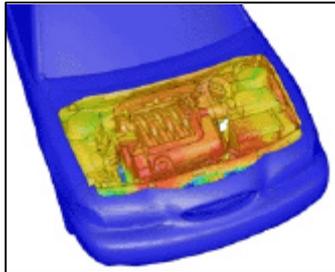
Examples of Simulation and High Performance Computing (HPC)

Power

Simulation of stress and vibrations of turbine assembly for use in nuclear power generation



Automotive

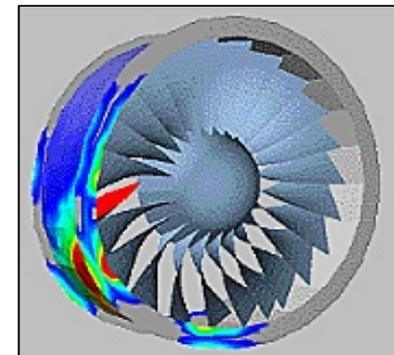


Simulation of underhood thermal cooling for decrease in engine space and increase in cabin space and comfort

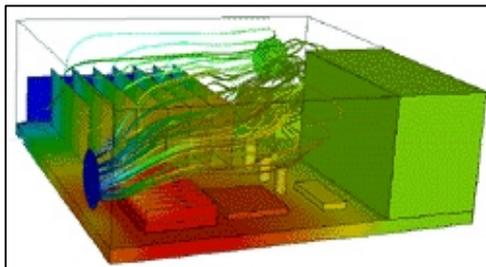


Aerospace

Evaluation of dual bird-strike on aircraft engine nacelle for turbine blade containment studies



Electronics



Evaluation of cooling air flow behavior inside a computer system chassis

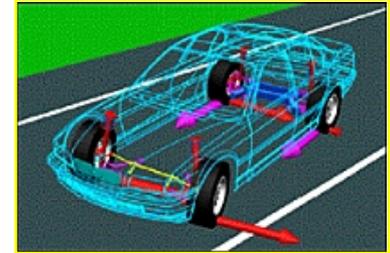


Examples of Computer Aided Engineering (CAE) and Simulation Software

Mechanical motion: **Multibody kinetics and dynamics**

ADAMS®

DADS



Implicit Finite Element Analysis: **Linear and nonlinear statics, dynamic response**

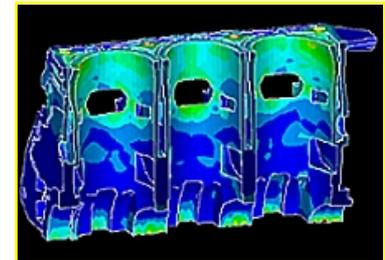
MSC.Nastran™, MSC.Marc™

ANSYS®

Pro MECHANICA

ABAQUS® Standard and Explicit

ADINA

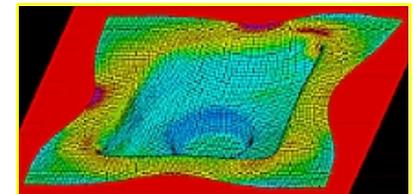


Explicit Finite Element Analysis : **Impact simulation, metal forming**

LS-DYNA

RADIOSS

PAM-CRASH®, PAM-STAMP



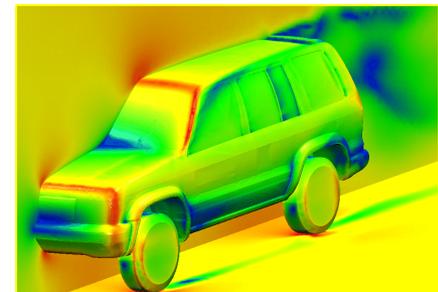
General Computational Fluid Dynamics: **Internal and external flow simulation**

STAR-CD

CFX-4, CFX-5

FLUENT®, FIDAP™

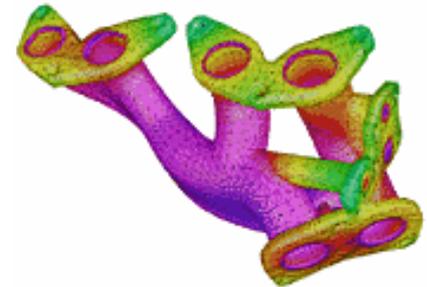
PowerFLOW®



Examples of Computer Aided Engineering (CAE) and Simulation Software (cont.)

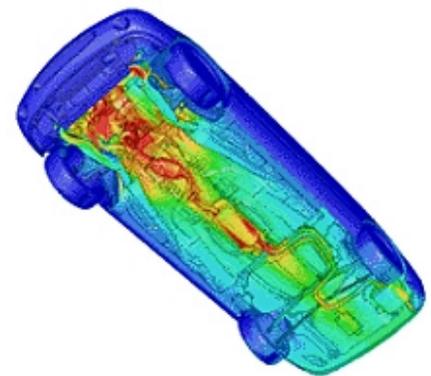
Preprocessing: Finite Element Analysis and Computational Fluid Dynamics mesh generation

ICEM-CFD
Gridgen
Altair® HyperMesh®
I-deas®
MSC.Patran
TrueGrid®
GridPro
FEMB
ANSA

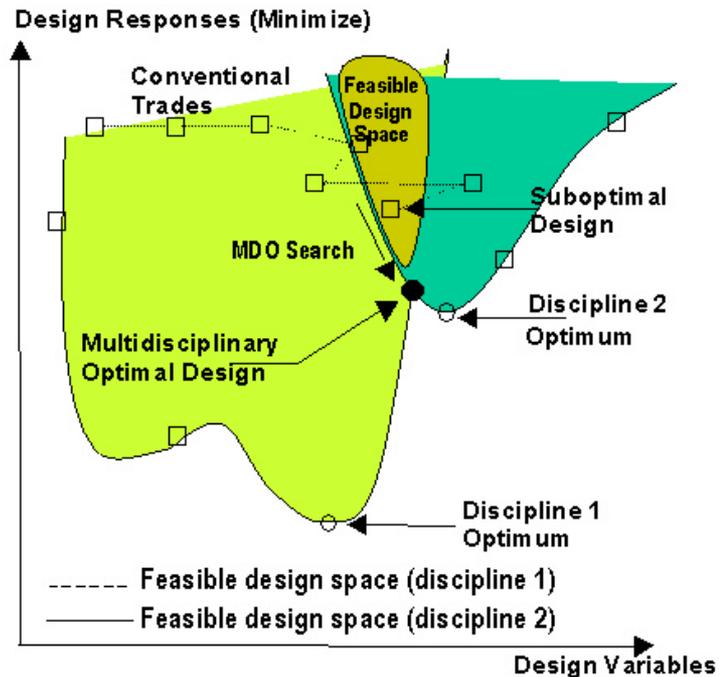


Postprocessing: Finite Element Analysis and Computational Fluid Dynamics results visualization

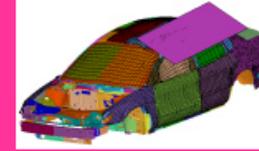
Altair® HyperMesh®
I-deas
MSC.Patran
FEMB
EnSight
FIELDVIEW
ICEM CFD Visual3 2.0 (PVS)
COVISE



Multidisciplinary Design Optimization (MDO): A Design Process Application



- CFD
- Structures
- Performance
- Controls
- Cost



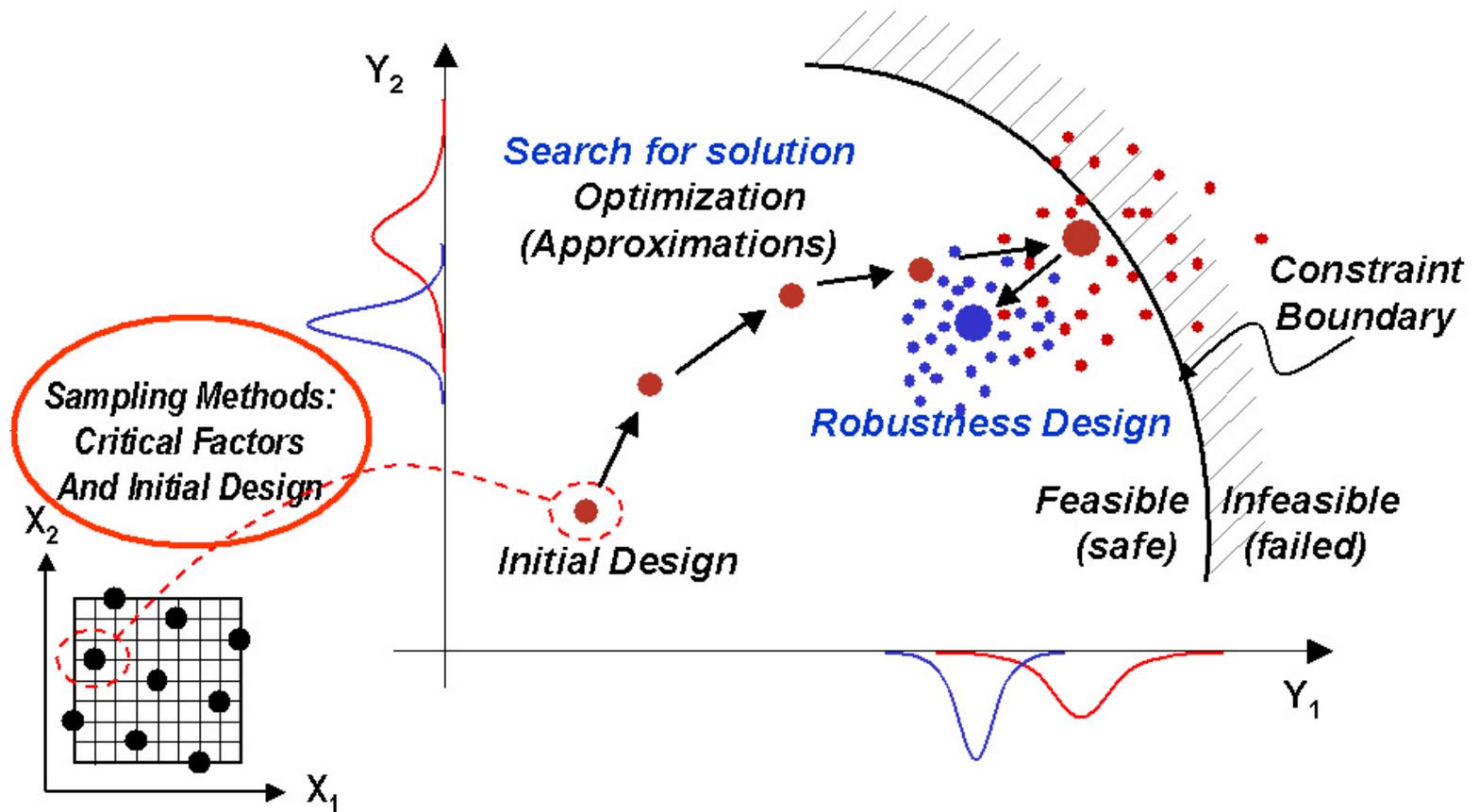
- NVH
- Safety
- Durability
- Controls Stability
- Cost

Key Elements of MDO

- Massive Computational Problem;
- Solution by decomposition effective for complex systems;
- Multiprocessor computing simplifies MDO solutions conceptually & enables solutions previously intractable;
- Aids in the management of the design process.

Mastery of interactions between the disciplines (or, subsystems) is as important as the methods & tools used within a single discipline

MDO: A Design Improvement Process



Environments Where MDO/HPC Is Beneficial

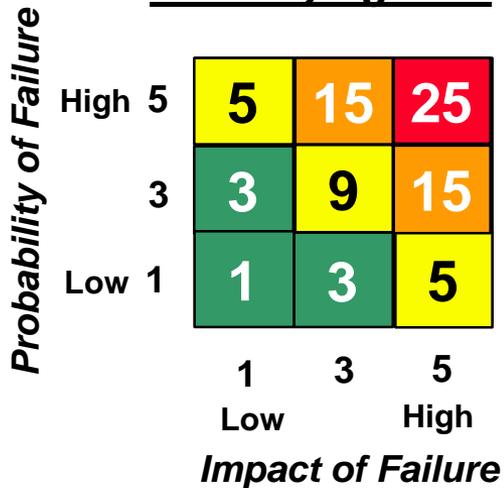
Design of complex vehicles & systems results in a simulation environment with:

- **A high number of design variables**
- **A substantial number of design subsystems and engineering disciplines**
- **Interdependency and interaction between the subsystems**
- **High resolution, complex models across several engineering disciplines**

Risk Assessment

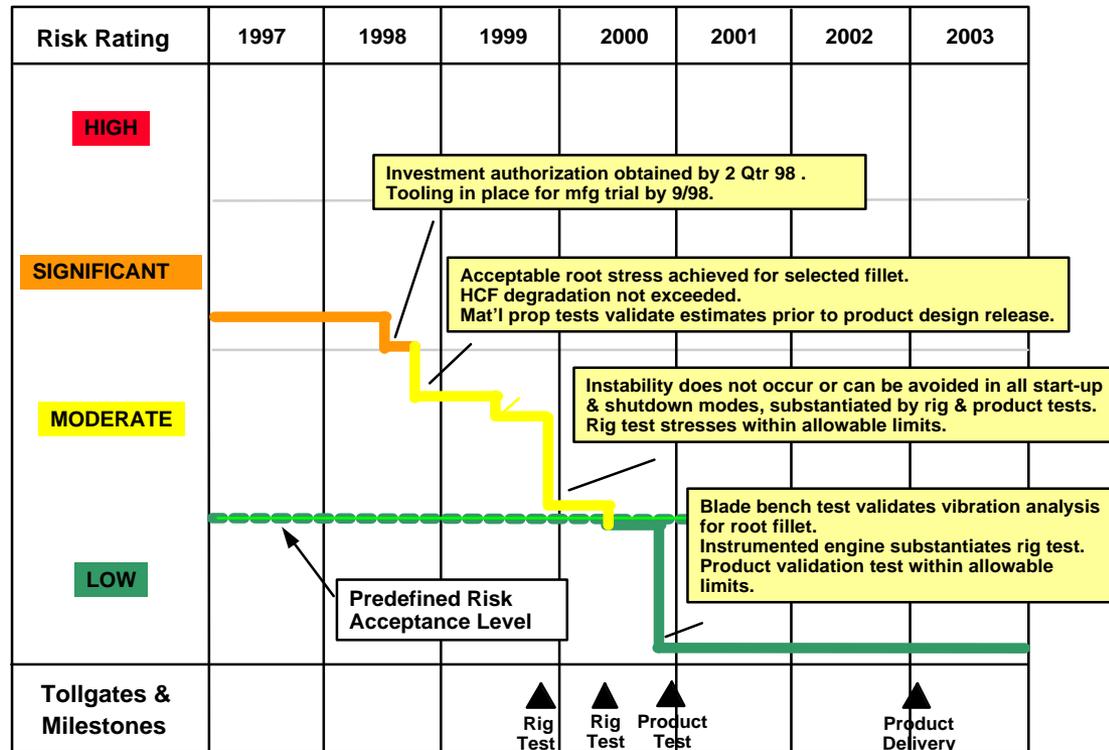
- Assess risks of key areas: technology, cost, schedule, market, etc.
- Use formal tools: FMEA, etc.
- Quantify risks: probability of failure and impact of failure
- Formulate responsive projects to reduce high risks
- Track progress with quantitative risk “waterfall”

Quantifying Risk



- R** Show stopper
- O** Significant risk
- Y** Fix before production
- G** Proceed with caution

Tracking Risk



Characteristics of a Successful DFSS Implementation

- **Commitment and leadership from the top**
- **Measurable, “stretch” goals for each project**
- **Accountability for project success**
- **Involvement and support of *everyone***
- **Training and implementing an extremely powerful, yet easy-to-use toolset for predicting quality and making tradeoffs before the product or process is even built**

- **It's very easy to focus on the last item...**
- **But, the first four – involving *leadership* and *cultural change* – are even more critical for success**